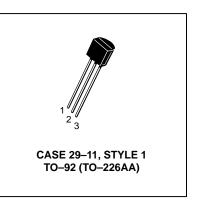
# Amplifier Transistor PNP Silicon

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit	
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	Vdc	
Emitter-Base Voltage	V <sub>EBO</sub>	-4.0	Vdc	
Collector Current — Continuous	Ι <sub>C</sub>	-100	mAdc	
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C	
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	PD	1.5 12	Watts mW/°C	
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	



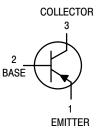
MPSA70

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Thermal Resistance, Junction to Ambient	$R_{\thetaJA}$	200	°C/W	
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	°C/W	

**ELECTRICAL CHARACTERISTICS** ( $T_{\Delta} = 25^{\circ}C$  unless otherwise noted)

Characteristic	Symb ol	Min	Мах	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage <sup>(1)</sup> ( $I_c = -1.0 \text{ mAdc}, I_B = 0$ )	V <sub>(BR)C</sub> EO	-40	_	Vdc
Emitter–Base Breakdown Voltage ( $I_E = -100 \ \mu Adc, I_C = 0$ )	V <sub>(BR)E</sub> BO	-4.0	_	Vdc
Collector Cutoff Current ( $V_{CB} = -30 \text{ Vdc}, I_E = 0$ )	I <sub>CBO</sub>	—	-100	nAdc

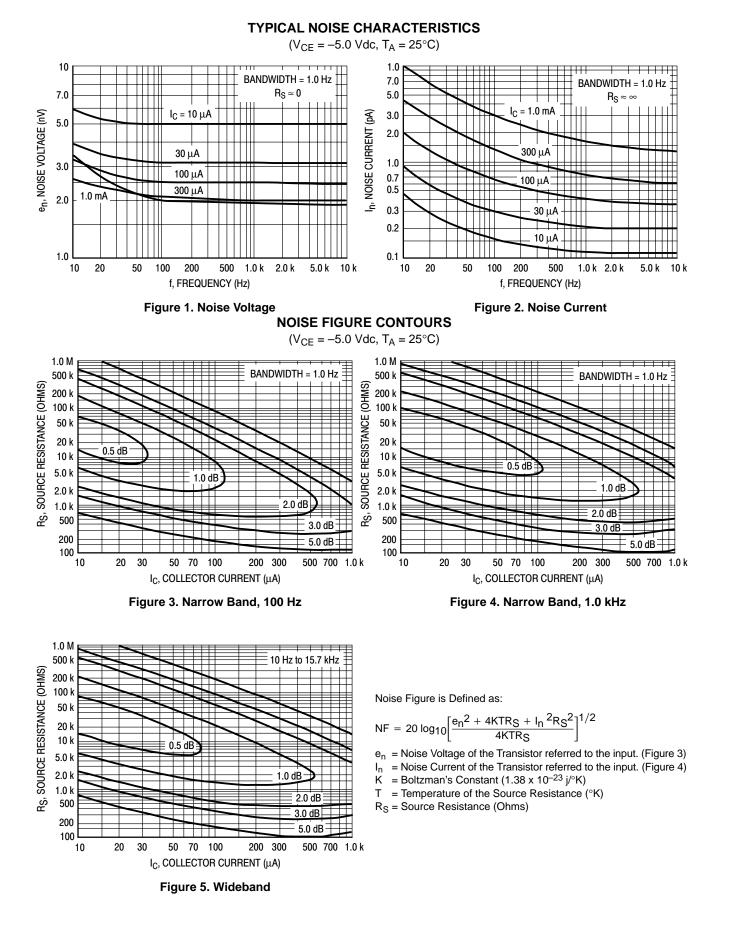


1. Pulse Test: Pulse Width  $\leq$  300 µs; Duty Cycle  $\leq$  2.0%.

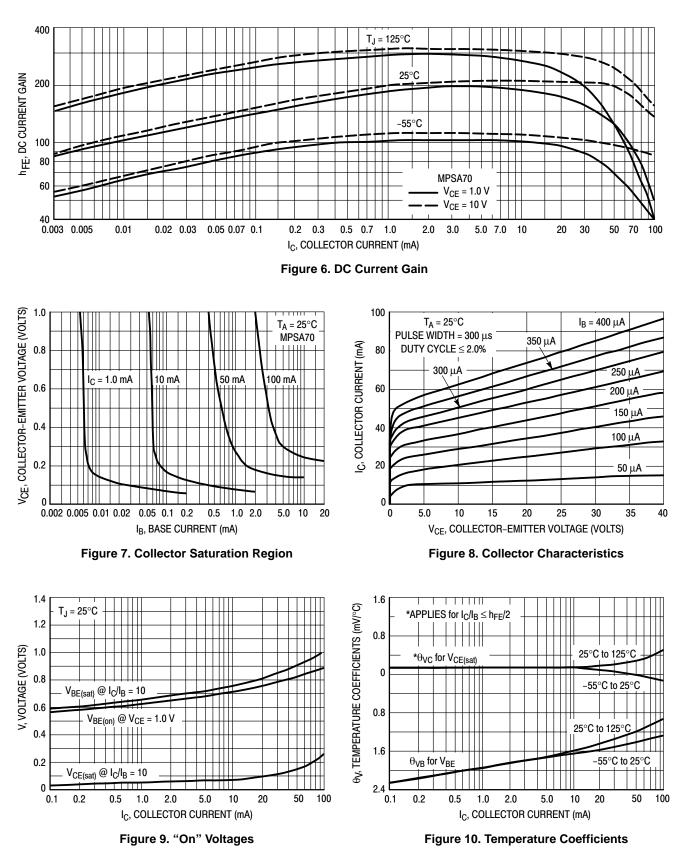
ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted) (Continued)

Characteristic	Symbol	Min	Max	Unit
ON CHARACTERISTICS				
DC Current Gain ( $I_C = -5.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$ )	h <sub>FE</sub>	40	400	—
Collector–Emitter Saturation Voltage $(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$	V <sub>CE(sat)</sub>	—	-0.25	Vdc
SMALL-SIGNAL CHARACTERISTICS	·			
Current–Gain — Bandwidth Product ( $I_C = -5.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 100 \text{ MHz}$ )	f <sub>T</sub>	125	—	MHz
Output Capacitance $(V_{CB} = -10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C <sub>obo</sub>	—	4.0	pF

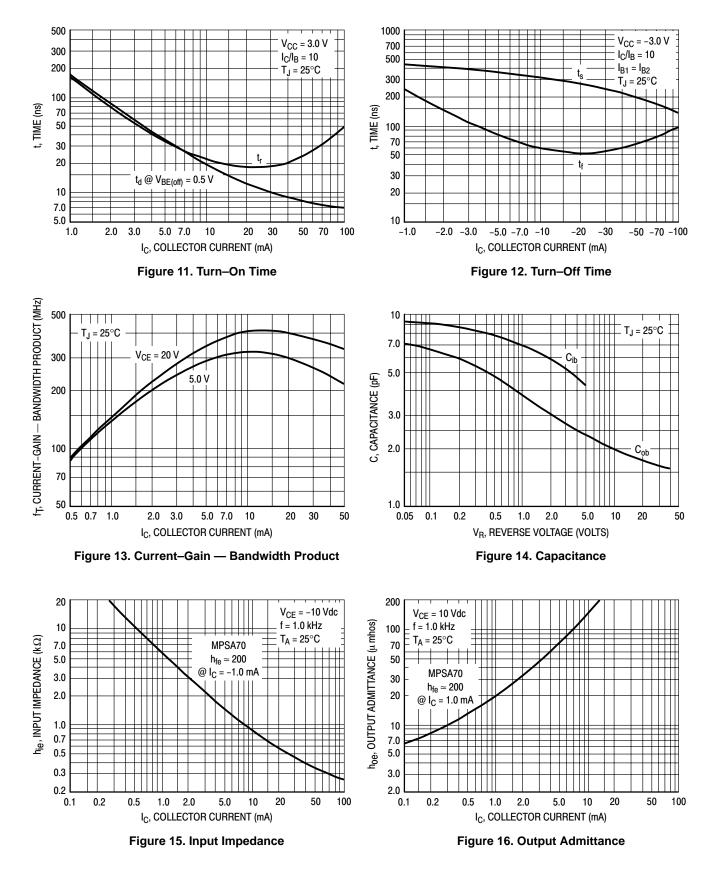


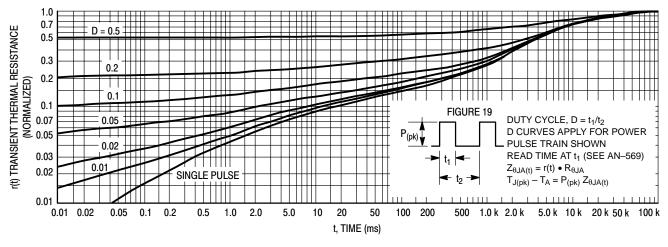






## **TYPICAL DYNAMIC CHARACTERISTICS**







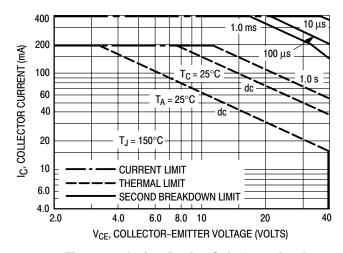


Figure 18. Active–Region Safe Operating Area

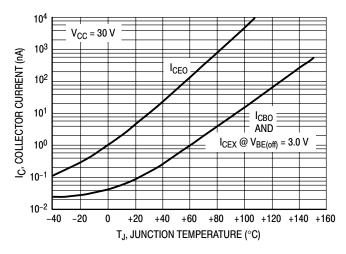


Figure 19. Typical Collector Leakage Current

The safe operating area curves indicate  $I_C-V_{CE}$  limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 18 is based upon  $T_{J(pk)} = 150^{\circ}$ C;  $T_{C}$  or  $T_{A}$  is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided  $T_{J(pk)} \leq 150^{\circ}$ C.  $T_{J(pk)}$  may be calculated from the data in Figure 17. At high case or ambient temperatures, thermal limitations will reduce the power than can be handled to values less than the limitations imposed by second breakdown.

### DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 17 was calculated for various duty cycles.

To find  $Z_{\theta JA(t)},$  multiply the value obtained from Figure 17 by the steady state value  $R_{\theta JA}.$ 

#### Example:

Dissipating 2.0 watts peak under the following conditions:

 $t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms} (D = 0.2)$ 

Using Figure 17 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

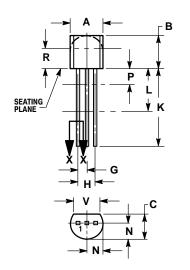
The peak rise in junction temperature is therefore

 $\Delta T = r(t) \ge P_{(pk)} \ge R_{\theta JA} = 0.22 \ge 2.0 \ge 200 = 88^{\circ}C.$ 

For more information, see AN-569.

## PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AL





STYLE 1: PIN 1. EMITTER 2. BASE 3. COLLECTOR

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
ſ	0.015	0.020	0.39	0.50
Κ	0.500		12.70	
L	0.250		6.35	
Ν	0.080	0.105	2.04	2.66
Ρ		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

## <u>Notes</u>

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